

SOP/SSOP/TSSOP 蓋印規範

Marking Specification for

SOP/SSOP/TSSOP

PC1-02-032

Rev. A
April, 2008

文件變更歷程表 Revision History

Rev. 版本	Initiated 制訂者	Approval Date 核准日期	Description 制定 / 修改內容		Page 頁碼	Reviewed 審核者
			Changed Reason 變更原因	Change Summarized 變更內容摘要		
A	Gerry Weng	2008/4/29	To fulfill ISO requirements	New initiation	All	Peter Yeh

審核 Signatures Required For Approval

Title / Name 職位 / 名稱	Approved 審核通過	Rejected (with Reason) 審核退回之原因	Date 日期
Production Manager Peter Yeh	V		2008/4/28
QA Director PS Yen	V		2008/4/28
Operation Div. VP Simon Leu	V		2008/4/29

分發單位 Distribution

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1 目的 Purpose :

- 1.1 To provide subcontractor instructions for the marking of PhaseLink product TYPES.
- 1.2 In order to ensure consistent presentation of the PhaseLink image, products will adhere to this specification with the exception of specific customer requirements
- 1.3 The following aspects are covered in this specification: marking content, marking location, letter type, abbreviations, customized marking, visual appearance, repair and resistance to

2 範圍與職責 Scope and Responsibility :

2.1 Scope 範圍 :

- 2.1.1 This specification is applicable to all marked integrated circuits for the SOP / SSOP / TSSOP packages.
- 2.1.2 This specification is applicable to all PhaseLink and/or subcontracted assembly and test centers which do product marking of PhaseLink products.

2.2 Responsibility 職責 :

- 2.2.1 Production department: Responsible for definition of marking rules, creation and maintenance of marking specifications and distribution to all subcontractors °

3 Applicable Document 應用文件 :

NA

4 Definition 名詞定義 :

- 4.1 Order Number: Product Number used for customer ordering.
- 4.2 Mark Number: Product Number used for marking.

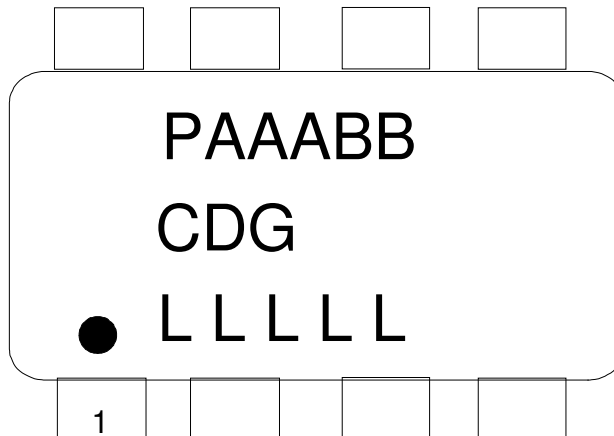
5 流程圖 Flowchart

NA

6 Work Instruction 作業說明 :

6.1 General marking format:

Front side marking: PLAAA – BB C D G - EE



6.1.1 Line 1:

- 6.1.1.1 P : PhaseLink
- 6.1.1.2 AAA-BB : Part Number

6.1.2 Line 2:

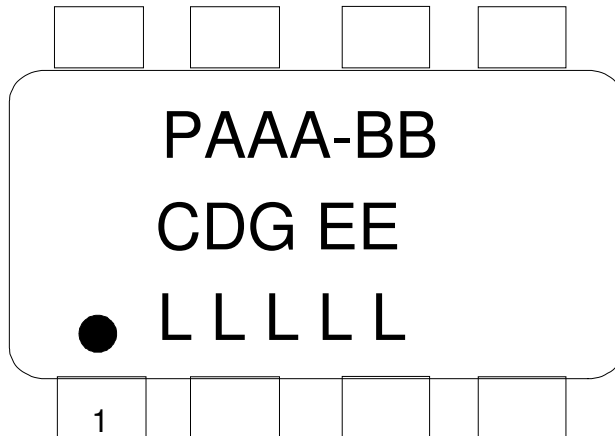
- 6.1.2.1 C : Package type. (refer to appendix 7.3)
- 6.1.2.2 D : Temperature. (refer to appendix 7.4)
- 6.1.2.3 G : Green indication (blank : Green / N : Non-green)

6.1.3 Line 3:

- 6.1.3.1 ● : Pin 1 identification dot (the dimension of pin 1 dot is 10 +/- 2 mils, and the color is white color, the distance between dot and package body edge is 10 ± 5 mils)
- 6.1.3.2 LLLLL : Production Lot No. (refer to appendix 6.5)

6.2 500A/501A/502A/560B product family:

Front side marking: PLAAA – BB C D G – EE



6.2.1 Line 1:

- 6.2.1.1 P : PhaseLink
- 6.2.1.2 AAA-BB : Part Number

6.2.2 Line 2:

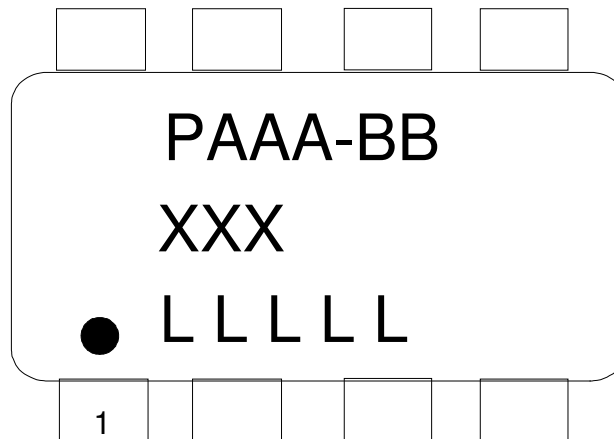
- 6.2.2.1 C : Package type. (refer to appendix 7.3)
- 6.2.2.2 D : Temperature. (refer to appendix 7.4)
- 6.2.2.3 G : Green indication (L: Green / blank : Non-green)
- 6.2.2.4 EE : Revision of part number (2 digits, e.g. A0 ~ Z9)

6.2.3 Line 3:

- 6.2.3.1 ● : Pin 1 identification dot (the dimension of pin 1 dot is 10 ± 2 mils, and the color is white color, the distance between dot and package body edge is 10 ± 5 mils)
- 6.2.3.2 LLLLL : Production Lot No. (refer to appendix 7.5)

6.3 Programmable device without PL611 product:

Front side marking: PLAAA – BB - XXX C D G - EE



6.3.1 Line 1:

- 6.3.1.1 P : PhaseLink
- 6.3.1.2 AAA-BB : Part Number

6.3.2 Line 2:

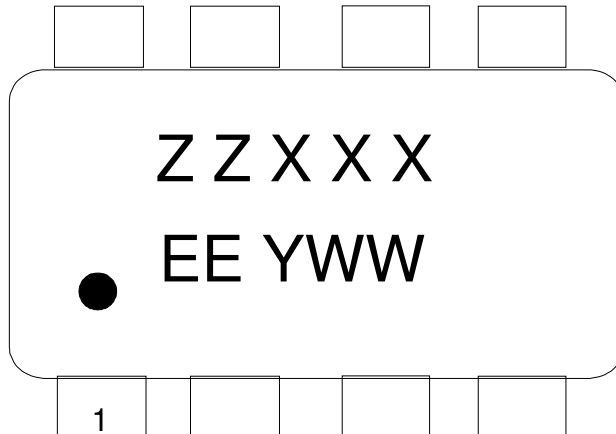
- 6.3.2.1 XXX : Programmable ID code (3 digits, please refer to appendix 7.2)

6.3.3 Line 3:

- 6.3.3.1 ● : Pin 1 identification dot (the dimension of pin 1 dot is 10 ± 2 mils, and the color is white color, the distance between dot and package body edge is 10 ± 5 mils)
- 6.3.3.2 LLLLL : Production Lot No. (5 digits, the detail please refer to appendix 7.5)

6.4 Programmable device for PL611 product:

Front side marking: PLAAA – BB - XXX C D G - EE



6.4.1 Line 1:

6.4.1.1 ZZ : Marking Number (2 digits, please refer to appendix 7.1)

6.4.1.2 XXX : Programmable ID code (3 digits, please refer to appendix 6.1 and 7.2)

6.4.2 Line 2:

6.4.2.1 EE : Revision of part number (2 digits, e.g. A0 ~ Z9)

6.4.2.2 YWW : Date code (3 digits; Y means year e.g. 8 means year 2008, WW means week code, e.g. 01 means WK01...)

6.4.3 ● : Pin 1 identification dot (the dimension of pin 1 dot is 10 ± 2 mils, and the color is white color, the distance between dot and package body edge is 10 ± 5 mils)

7 Appendix 附錄：

7.1 Part number & marking list:

Product Family	Part Number	Marking (ZZXXX)
C611	PL611-01-XXX	C1XXX
	PL611-20-XXX	C2XXX
	PL611-30-XXX	C3XXX
	PL611-31-XXX	C4XXX
	PL611-05-XXX	C5XXX
	PL611-12-XXX	C6XXX
	PL611-07-XXX	C7XXX

7.2 ID Code:

Code	Purpose
000~Z99	Programming code

7.3 Package Type:

Code	Package Type
S	SOP8L /16L: 150 mil
X	SSOP: 150/209/300 mil
O	TSSOP8L /16L: 173 mil

7.4 Temperature:

Code	Temperature
C	Commercial
I	Industrial

7.5 Production lot number:

7.5.1 Total five digitals.

7.5.2 1st number: Foundry code.

7.5.3 2nd number: Subcontractor code.

7.5.4 3rd to 5th numbers: series number such as 001 ~ Z99

7.6 Wafer foundry code:

Code	Subcontractor
A	Chartered
B	UMC

7.7 Assembly subcontractor code:

Code	Subcontractor
A	CET
O	TICP
Q	Sigurd
S	TMC
T	Greatek
U	UNISEM
W	YTEC